MSKSEMI 美森科













FSD

T\/9

TSS

MOV

GDT

PIFD

2SA2029

Product specification





General Description

- This PNP transistor is designed for general purpose amplifier
- applications. This device is housed in the SOT-723 package which is
- designed for low power surface mount applications, where

General Features

- Reduces Board Space
- High hFE, 210-460 (Typical)
- Low VCE(sat), < 0.5 V
- ESD Performance: Human Body Model; 2000 V,
- Machine Model; > 200 V
- Available in 4 mm, 8000 Unit Tape & Reel
- This is a Pb-Free Device

Reference News

PACKAGE OUTLINE	Pin Configuration	Mar	king
MENERAL MARKET M	COLLECTOR	FR	FQ
SOT-723	BASE EMITTER	2SA2029-R-MS	2SA2029-Q-MS



MAXIMUM RATINGS(Ta = 25°C)

Rating	Symbol	Value	Unit
Collector-Base Voltage	V(BR)CBO	-60	Vdc
Collector-Emitter Voltage	V(BR)CEO	-50	Vdc
Emitter-Base Voltage	V(BR)EBO	-6.0	Vdc
Collector Current - Continuous	lc	- 100	mAdc

THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Power Dissipation (Note 1)	Po	265	W
Junction Temperature	TJ	150	°C
Storage Temperature Range	Tstg	- 55 ~ + 150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Device mounted on a FR-4 glass epoxy printed circuit board using the minimum recommended footprint.

ELECTRICAL CHARACTERISTICS (TA = 25°C)

Characteristic	Symbol	Min	Тур	Max	Unit
Collector-Base Breakdown Voltage (IC = -50 MAdc, IE = 0)	V(BR)CBO	-60	-	-	Vdc
Collector-Emitter Breakdown Voltage (I _C = - 1.0 mAdc, I _B = 0)	V(BR)CEO	-50	-	-	Vdc
Emitter-Base Breakdown Voltage (I _E = −50	V(BR)EBO	-6.0	-	-	Vdc
Collector-Base Cutoff Current (VcB = -30 Vdc, IE = 0)	Ісво	-	_	-0.5	n A
Emitter-Base Cutoff Current (VEB = -7.0 Vdc, IB = 0)	I _{EBO}	-	-	-0.1	μA
Collector-Emitter Saturation Voltage (Note 2) (Ic = -50 mAdc, IB = -5.0 mAdc)	VCE(sat)	-	-	-0.5	Vdc
DC Current Gain (Note 2) (VCE = -6.0 Vdc, IC = - 1.0 mAdc)	h _{FE}	120	-	560	-
Transition Frequency (VCE = -12 Vdc, IC = -2.0 mAdc, f = 30 MHz)	f _T	_	140	-	MHz
Output Capacitance (V _{CB} = - 12 Vdc, I _E = 0 Adc, f = 1.0 MHz)	Сов	-	3.5	-	P _F

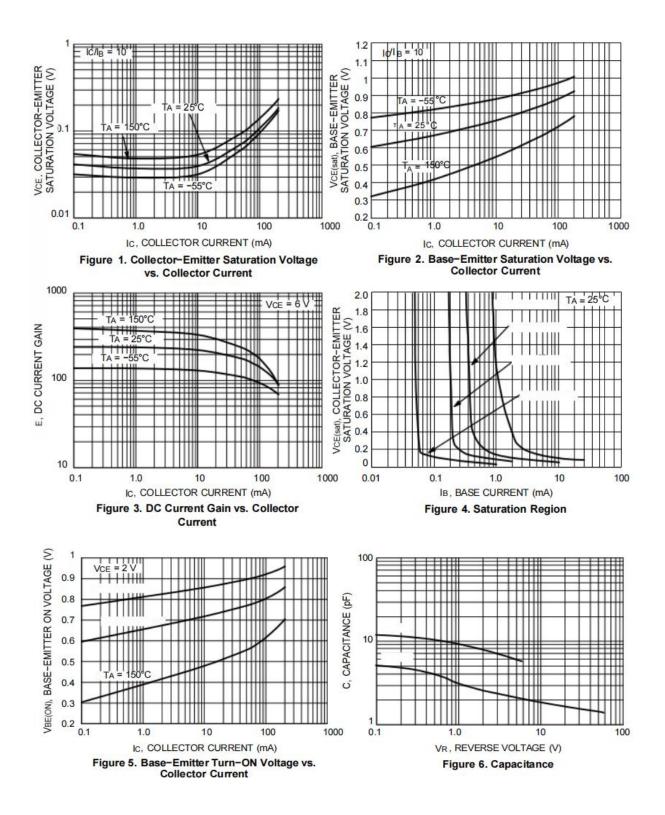
^{2.} Pulse Test: Pulse Width ≤ 300 µs, Duty Cycle ≤ 2%.

HFE 值分类如下:QR

*	Q	R	
hFE	120~270	180~390	



ELECTRICAL CHARACTERISTICS CURVES





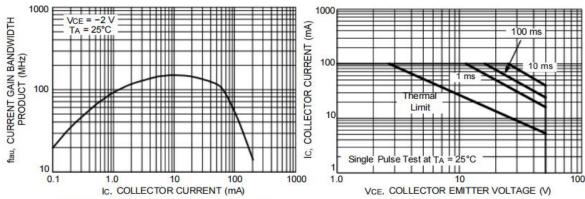
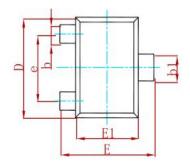


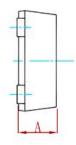
Figure 7. Current Gain Bandwidth Product vs. Collector Current

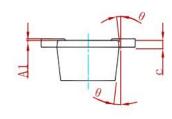
Figure 8. Safe Operating Area



PACKAGE MECHANICAL DATA

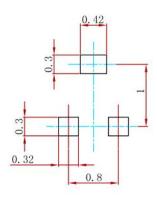






Symbol	Dimensions	In Millimeters	Dimensions	In Inches
Symbol	Min.	Max.	Min.	Max.
Α	0.430	0.500	0.017	0.020
A1	0.000	0.050	0.000	0.002
b	0.170	0.270	0.007	0.011
b1	0.270	0.370	0.011	0.015
С	0.080	0.150	0.003	0.006
D	1.150	1.250	0.045	0.049
Е	1.150	1.250	0.045	0.049
E1	0.750	0.850	0.030	0.033
е	0 800)TYP	0 031	TYP
θ	7° F	REF.	7° R	EF.

Suggested Pad Layout



Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
2SA2029	SOT-723	8000



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